

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4336678

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JEONG SOO YEA	03/02/2017
SANG JUN JUNG	03/02/2017
KYONG ROK KANG	03/02/2017
DONG OH MIN	03/02/2017
IN YOUL SEO	03/02/2017
SUNG JIN JANG	03/02/2017
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD
Street Address:	129, SAMSUNG-RO
Internal Address:	YEONGTONG-GU, SUWON-SI
City:	GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15514477
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-628-3600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	SAMS14-50554
NAME OF SUBMITTER:	MICHAEL G. RODRIGUEZ
SIGNATURE:	/Michael G. Rodriguez/
DATE SIGNED:	03/24/2017

Total Attachments: 2

source=Assignment#page1.tif

source=Assignment#page2.tif

ASSIGNMENT

WHEREAS, We, Jeong Soo Yea, resident of Gwangsan-gu, Gwangju, Republic of Korea, citizen of Republic of Korea, Sang Jun Jung, resident of Hwaseong-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Kyong Rok Kang, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Dong Oh Min, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, In Youl Seo, resident of Yongin-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, and Sung Jin Jang, resident of Yongin-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a "APPARATUS FOR MOLDING GLASS AND METHOD FOR MOLDING" disclosed in an application for United States Letters Patent (Application Serial No. ___/_____, filed on _____, said application having been executed concurrently herewith;


WHEREAS, SAMSUNG ELECTRONICS CO., LTD, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 16677, Republic of Korea (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEE of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

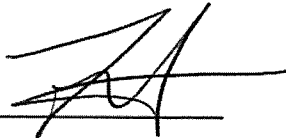
We hereby further agree that we will communicate to said ASSIGNEE, or to its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: 2017.3.2



Jeong Soo Yea

Date: 2017.3.2




Sang Jun Jung

Date: 2017.3.2




Kyong Rok Kang

Date: 2017.3.2



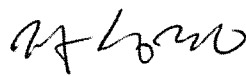
Dong Oh Min

Date: 2017.3.2



In Youl Seo

Date: 2017.3.2



Sung Jih Jang